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Data sheet acquired from Harris Semiconductor SCHS071

CMOS Presettable Up/Down Counters

High-Voltage Types (20-Volt Rating)
CD4510B — — BCD Type
CD4516B — — Binary Type

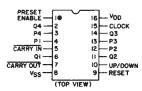
CD4510B Presettable BCD Up/Down Counter and the CD4516 Presettable Binary Up/Down Counter consist of four synchronously clocked D-type flip-flops (with a gating structure to provide T-type flip-flop capability) connected as counters. These counters can be cleared by a high level on the RESET line, and can be preset to any binary number present on the jam inputs by a high level on the PRESET ENABLE line. The CD4510B will count out of non-BCD counter states in a maximum of two clock pulses in the up mode, and a maximum of four clock pulses in the down mode.

If the CARRY-IN input is held low, the counter advances up or down on each positive-going clock transition. Synchronous cascading is accomplished by connecting all clock inputs in parallel and connecting the CARRY-OUT of a less significant stage to the CARRY-IN of a more significant stage.

The CD4510B and CD4516B can be cascaded in the ripple mode by connecting the CARRY-OUT to the clock of the next stage. If the UP/DOWN input changes during a terminal count, the CARRY-OUT must be gated with the clock, and the UP/DOWN input must change while the clock is high. This method provides a clean clock signal to the subsequent counting stage. (See Fig. 15).

These devices are similar to types MC14510 and MC14516.

The CD4510B and CD4516B Series types are supplied in 16-lead hermetic dual-in-line ceramic packages (D and F suffixes), 16-lead dual-in-line plastic packages (E suffix), and in chip form (H suffix).

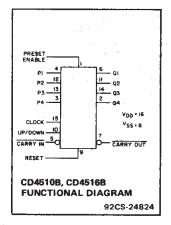


CD4510B, CD4516B
TERMINAL ASSIGNMENT

CD4510B, CD4516B Types

Features:

- Medium-speed operation -f_{CL} = 8 MHz typ. at 10 V
- Synchronous internal carry propagation
- Reset and Preset capability
- 100% tested for quiescent current at 20 V
- 5-V, 10-V, and 15-V parametric ratings
- Standardized symmetrical output characteristics
- Maximum input current of 1 μA at 18 V over full package temperature range;
 100 nA at 18 V and 25°C
- Noise margin (full package-temperature range): 1 V at V_{DD} = 5 V
 2 V at V_{DD} = 10 V
 2.5 V at V_{DD} = 15 V
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"



Applications:

- Up/Down difference counting
- Multistage synchronous counting
- Multistage ripple counting
- Synchronous frequency dividers

OPERATING CONDITIONS AT TA = 25°C, Unless Otherwise Specified

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges.

Characteristic	V _{DD}	Min.	Max.	Units
Supply Voltage Range (At TA = Full Package-Temperature Range)		3	18	V
	5	150		
Clock Pulse Width, t _W	10	75	-	ns
	15	60	-	
	5	_	2	
Clock Input Frequency, fCL	10	-	4	MHz
	15	-	5.5	
	5	150	_	
Preset Enable or Reset Removal Time	10	80	- 1	กร
	15	60	-	
	5	_	15	
Clock Rise and Fall Time, t _r CL, t _f CL*	10 15	_	5 5	μs
	5	130	_	
Carry-In Setup Time, t _S	10	60	- 1	ns
	15	45	_	
	5	360		
Up-Down Setup Time, t _S	10	160	-	ns
	15	110	_	
	5	220	_	
Preset Enable or Reset Pulse Width, tw	10	100	_	ns
		75	_	

Time required after the falling edge of the reset or preset enable inputs before the rising edge of the clock will trigger the counter (similar to setup time).

^{*}If more than one unit is cascaded in the parallel clocked application, t_rCL should be made less than or equal to the sum of the fixed propagation delay at 15 pF and the transition time of the carry output driving stage for the estimated capacitive load.

MAXIMUM RATINGS, Absolute-Maximum Values:	
DC SUPPLY-VOLTAGE RANGE, (VDD)	
Voltages referenced to VSS Terminal)	0.5V to +20V
INPUT VOLTAGE RANGE, ALL INPUTS	0.5V to V _{DD} +0.5V
DC INPUT CURRENT, ANY ONE INPUT	±10mA
POWER DISSIPATION PER PACKAGE (PD):	
For T _A = -55°C to +100°C	500mW
For T _A = +100°C to +125°C	Derate Linearity at 12mW/°C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR	
FOR TA = FULL PACKAGE-TEMPERATURE RANGE (All Package	Types) 100mW
OPERATING-TEMPERATURE RANGE (TA)	55°C to +125°C
STORAGE TEMPERATURE RANGE (Tstg)	65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):	
At distance $1/16 \pm 1/32$ inch $(1.59 \pm 0.79$ mm) from case for 10s m	ax+265°C

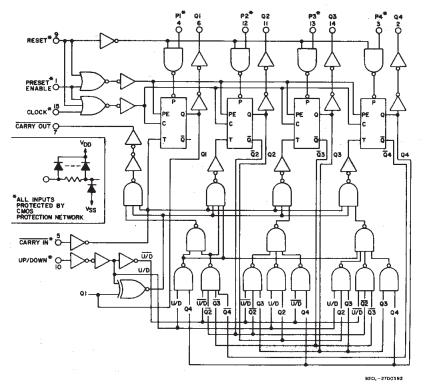


Fig.3 - Logic Diagram for CD4510B.

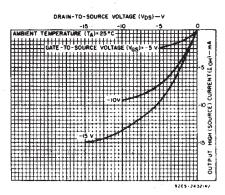


Fig.5 – Minimum output high (source) current characteristics.

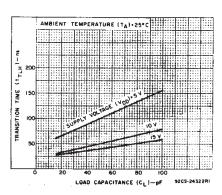


Fig.6 — Typical transition time vs. load capacitance.

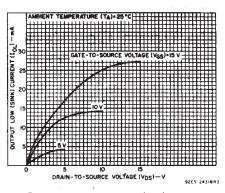


Fig.1 – Typical output low (sink) current characteristics.

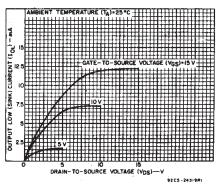


Fig. 2 – Minimum output low (sink) current characteristics.

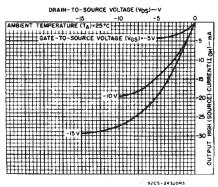


Fig.4 - Typical output high (source) current characteristics.

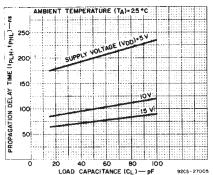
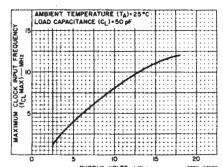


Fig. 7 — Typical propagation delay time vs. load capacitance for clock-to-Q outputs,

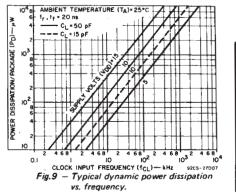
STATIC ELECTRICAL CHARACTERISTICS

CHARACTER-	COND	is	LIMITS AT INDICATED TEMPERATURES (°C)										
ISTIC	Vo	VIN	V _{DD} (V)					+25			UNITS		
	(V)	(V)		-55	-40	+85	+125	Min.	Тур.	Max.	L		
Quiescent Device	_	0,5	5	5	5	150	150	-	0.04	5	μΑ.		
Current,	_	0,10	10	10	10	300	300	-	.0.04	10			
IDD Max.	_	0,15	15	20	20	600	600	-	0.04	20			
	-	0,20	20	-100	100	3000	3000	-	0.08	100			
Output Low	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	-			
(Sink) Current	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	-			
IOL Min.	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	_	1		
Output High	4.6	0,5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	-	mA		
(Source)	2.5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	-			
Current, IOH Min.	9.5	0,10	10	-1.6	~1.5	-1.1	-0.9	-1.3	-2.6	-			
TOH MITT.	13.5	0,15	15	4.2	-4	-2.8	-2.4	-3.4	-6.8	-			
Output Voltage:	-	0,5	5	0.05				-	- 0	0.05			
Low-Level, VOL Max.	_	0,10	10	0.05					0	0.05	V		
AOF Max		0,15	15	0.05				-	0	0.05			
Output Voltage:	_	0,5	5	4.95				4.95	- 5	-	·		
High-Level,	_	0,10	10	9.95				9.95	10	-			
VOH Min.	_	0,15	15		14	.95		14.95	15	-			
Input Low Voltage, VIL Max.	0.5, 4.5		5	1,5				_	_	1.5			
	1, 9	_	10	3				_	_	3			
	1.5,13.5	_	15	4				-		4			
Input High Voltage, VIH Min.	0.5, 4.5	-	5	3.5				3.5	_	_	V		
	1, 9		10	7				7	_	_			
	1.5,13.5	-	15	11				11	_	_	┙		
Input Current IJN Max.	_	0,18	18	±0.1	±0.1	±1	±1	-	±10-5	±0.1	μΑ		



SUPPLY VOLTS -- VDD 92CS-27006

Fig. 8 -- Typical maximum clock input frequency vs. supply voltage.



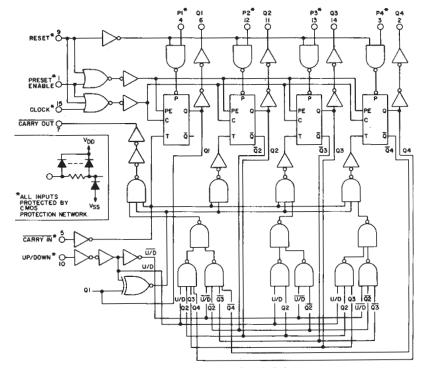


Fig. 16 - Logic Diagram for CD4516B.

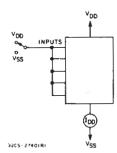


Fig. 11 — Quiescent-device-current test circuit.

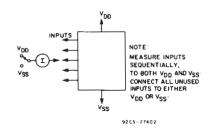


Fig. 12 - Input-current test circuit.

92CL - 27004#2

DYNAMIC ELECTRICAL CHARACTERISTICS at T $_A$ = 25°C, C $_L$ = 50 pF, Input t $_r$, t $_f$ = 20 ns, R $_L$ = 200 k Ω

Characteristic	Conditions VDD (V)	A Min.	Units		
Propagation Delay Time (tpHL, tpLH):	177	ivilli.	Тур.	Max.	
Propagation Delay Time (tPHL, tPLH):	5		200	400	
Clock-to-Q Output (See Fig. 10)	10 15	_ _	100 75	200 150	ns
Preset or Reset-to-Q Output	5 10 15	- - -	210 105 80	420 210 160	ns
Clock-to-Carry Out	5 10 15	_ _ _	240 120 90	480 240 180	กร
Carry-In-to-Carry Out	5 10 15	- - -	125 60 50	250 120 100	ns
Preset or Reset-to-Carry Out	5 10 15	- -	320 160 125	640 320 250	ns
Transition Time (t _{THL} , t _{TLH}) (See Fig. 9)	5 10 15	_ 	100 50 40	200 100 80	ns
Max. Clock Input Frequency (fCL)	5 10 15	2 4 5.5	4 8 11	- - -	MHz
Input Capacitance (CIN)		-	5	7.5	pF
Set-up Time, t _S Preset Enable to J _n	5 10 15	25 10 10	12 6 5	<u>-</u> -	
Hold times, t _H Clock to Carry-In	5 10 15	60 30 30	30 4 1		ns
Clock to Up/Down	5 10 15	30 30 30	10 4 5	_ _ _	,
Preset Enable to J _n	5 10 15	70 40 40	35 20 20		

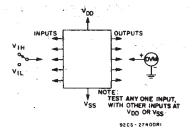
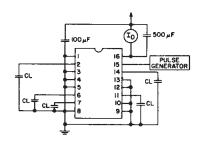


Fig. 13 - Input-voltage test circuit.



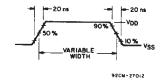
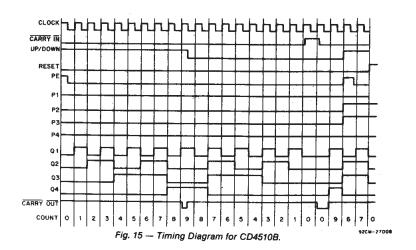


Fig. 14 - Power-dissipation test circuit and input waveform.



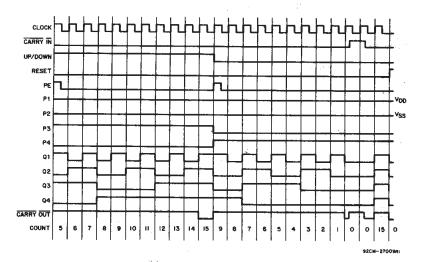
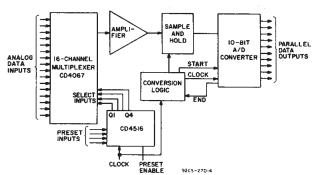


Fig. 16 — Timing diagram for CD4516B.

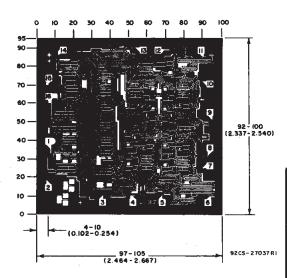


This acquisition system can be operated in the random access mode by jamming in the channel number at the present inputs, or in the sequential mode by clocking the CD4516B.

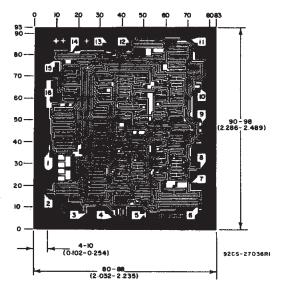
Fig. 17 — Typical 16-channel, 10-bit data acquisition system.

CL	CI	U/D	PE	R	ACTION				
X	1	Х	0		NO COUNT				
7	0	_1	0	0	COUNT UP				
	0	0	Ó	0	COUNT DOWN				
X	X	Х	1	0	PRESET				
X	Х	X	X	1	RESET				
	V - DON'T CARE								

TRUTH TABLE

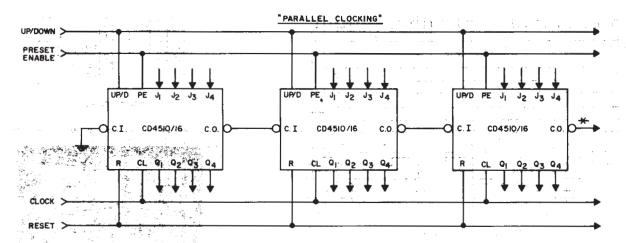


Dimensions and Pad Layout for CD4510BH.

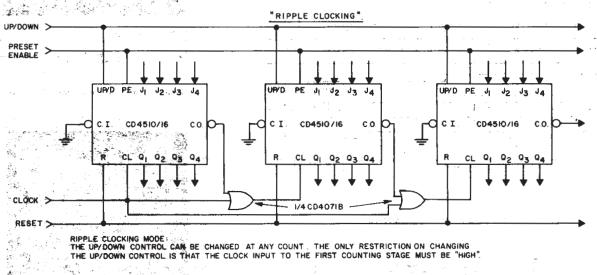


Dimensions and Pad Layout for CD4516BH.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch) .



* CARRY OUT lines at the 2nd, 3rd, etc., stages may have a negative-going glitch pulse resulting from differential delays of different CD4510/16 IC's. These negative-going glitches do not affect proper CD4510/16 operation. However, if the CARRY OUT signals are used to trigger other edge-sensitive logic devices, such as FF's or counters, the CARRY OUT signals should be gated with the clock signal using a 2-input OR gate such as CD4071B.



THE UP/DOWN CONTROL CAN BE CHANGED AT ANY COUNT. THE ONLY RESTRICTION ON CHANGING THE UP/DOWN CONTROL IS THAT THE CLOCK INPUT TO THE FIRST COUNTING STAGE MUST BE "HIGH".

For cascading sounters operating in a fixed up-count or down-count mode, the OR galled are green unred between stages, and CO is connected directly to the CL input of the Mail stage with CT grounded.

92CL-17194R5

Fig. 18 — Cascading counter packages.

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